



flowPACK 0

650 V / 75 A

Topology features

- Inverter
- Kelvin Emitter for improved switching performance
- Temperature sensor

Component features

- Easy paralleling
- Low collector emitter saturation voltage
- Low turn-off losses
- Positive temperature coefficient

Housing features

- Base isolation: Al₂O₃
- Clip-in, reliable mechanical connection, qualified for wave soldering
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Solder pin

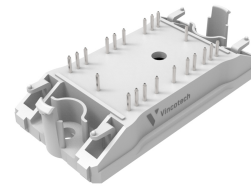
Target applications

- General Purpose Drives
- Heat Pumps
- Industrial Drives

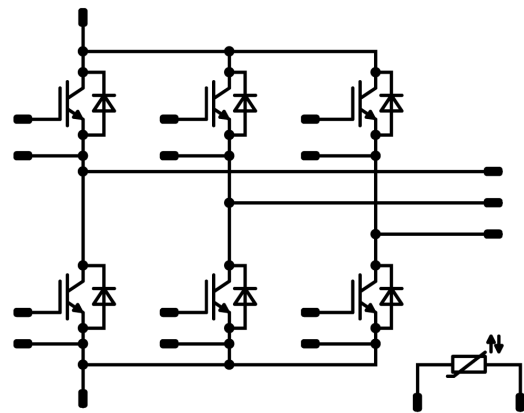
Types

- 10-FZ076PA075I7-P866F08

flow 0 12 mm housing



Schematic





Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		650	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	69	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	225	A
Turn off safe operating area		$T_j = 150\text{ °C}$, $V_{CE} = 1200\text{ V}$	225	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	95	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 400\text{ V}$ $T_j = 150\text{ °C}$	3	μs
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Inverter Diode

Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	51	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	225	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	72	W
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^{\circ}\text{C}$
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	$^{\circ}\text{C}$

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Creepage distance			>12,7	mm
Clearance			9,1	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	

Inverter Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00075	25	4,35	5	5,65	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		75	25 125 150		1,31 1,38 1,41	1,65 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	650		25			20	μA
Gate-emitter leakage current	I_{GES}		20	0		25			100	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}							4460		pF
Output capacitance	C_{oes}	$f = 1$ Mhz	0	25		25		135		pF
Reverse transfer capacitance	C_{res}							46		pF
Gate charge	Q_g	$V_{CC} = 520$ V	15		75	25		435		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						1		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$					25 125 150		152,65 158,03 159,15		ns
Rise time	t_r	$R_{gon} = 8$ Ω $R_{goff} = 8$ Ω				25 125 150		33,95 36,46 36,65		ns
Turn-off delay time	$t_{d(off)}$		±15	350	75	25 125 150		192,53 224,52 232,97		ns
Fall time	t_f					25 125 150		20,9 44,76 50,35		ns
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 1,29$ μC $Q_{tFWD} = 3,04$ μC $Q_{tFWD} = 3,55$ μC				25 125 150		1,92 2,58 2,69		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,07 1,68 1,85		mWs



Vincotech

10-FZ076PA075I7-P866F08
datasheet

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit	
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max			
Inverter Diode											
Static											
Forward voltage	V_F				75	25 125 150		1,8 1,73 1,7	2 ⁽¹⁾	V	
Reverse leakage current	I_R	$V_r = 650$ V				25			20	μA	
Thermal											
Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						1,31		K/W	
Dynamic											
Peak recovery current	I_{RM}	$di/dt=1907$ A/μs $di/dt=2002$ A/μs $di/dt=2230$ A/μs	±15	350	75	25		23,36		A	
						125		35,96			
						150		39,48			
Reverse recovery time	t_{rr}					25		99,46			ns
						125		141,54			
						150		154,78			
Recovered charge	Q_r					25		1,29		μC	
						125		3,04			
						150		3,55			
Reverse recovered energy	E_{rec}					25		0,204		mWs	
						125		0,544			
						150		0,655			
Peak rate of fall of recovery current	$(di_r/dt)_{max}$					25		124,93		A/μs	
						125		323,08			
						150		227,24			



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	V_{CE} [V]	I_D [A]	I_C [A]	T_j [°C]	Min	

Thermistor

Static

Rated resistance	R					25		22		kΩ
Deviation of R100	$A_{R/R}$	$R_{100} = 1484 \Omega$				100	-5		5	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 1 \%$						3962		K
B-value	$B_{(25/100)}$	Tol. $\pm 1 \%$						4000		K
Vincotech Thermistor Reference									I	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

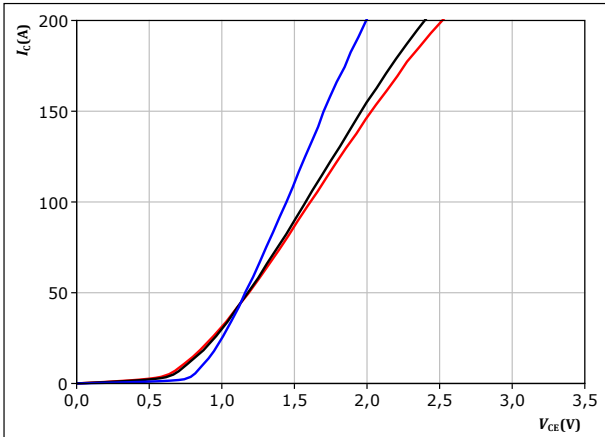


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

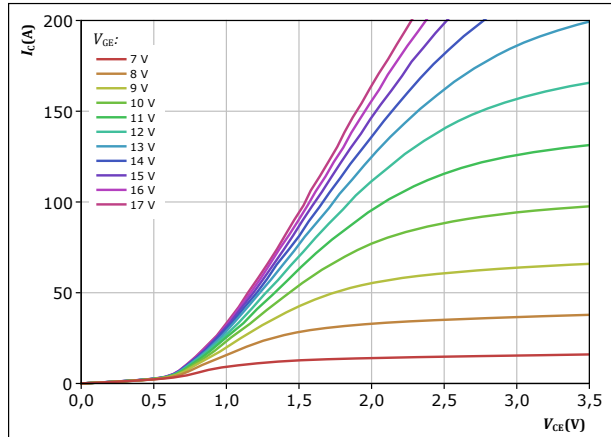


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

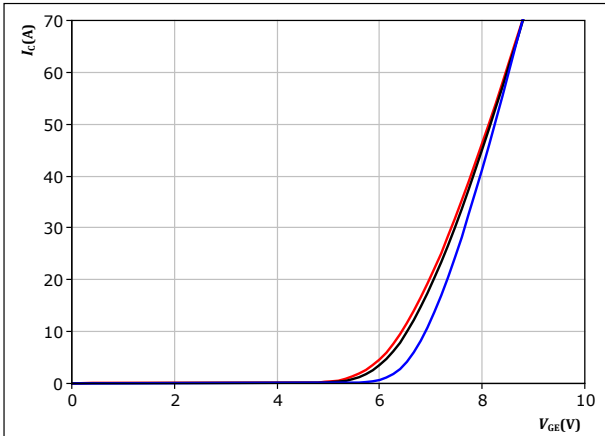


$t_p = 250 \mu s$
 $T_j = 150 \text{ °C}$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

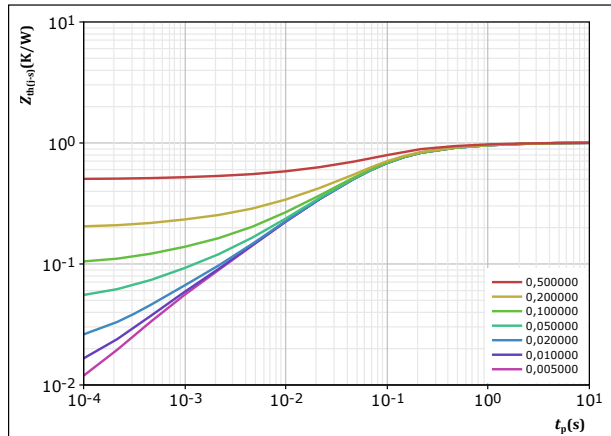


$t_p = 250 \mu s$
 $V_{CE} = 19 V$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,003 K/W$

IGBT thermal model values

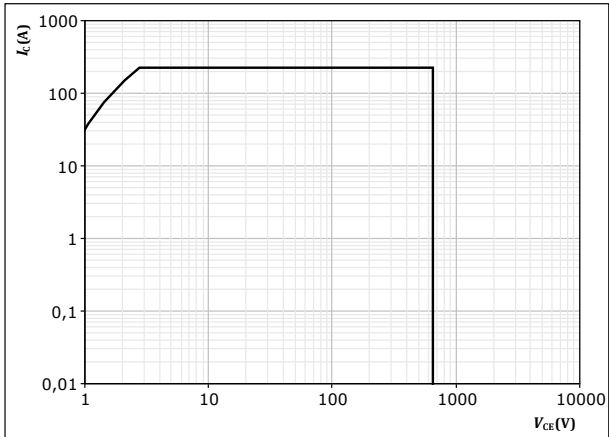
R (K/W)	τ (s)
6,83E-03	1,73E+01
7,18E-02	1,50E+00
1,95E-01	2,68E-01
5,24E-01	6,58E-02
1,31E-01	1,35E-02
4,74E-02	3,46E-03
2,89E-02	5,40E-04



Inverter Switch Characteristics

figure 5. IGBT

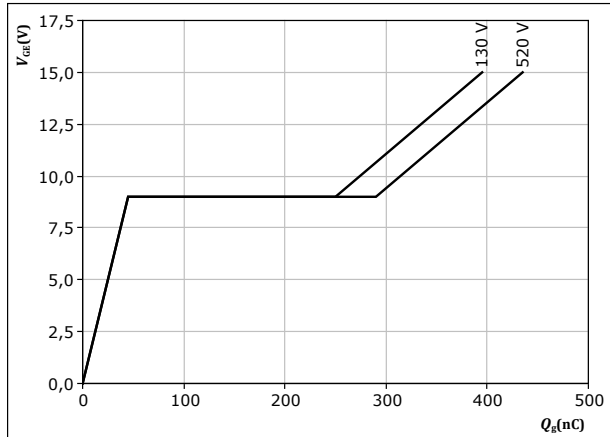
Safe operating area
 $I_C = f(V_{CE})$



$D =$ single pulse
 $T_s = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 6. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



$I_C = 75$ A
 $T_j = 25$ °C



Inverter Diode Characteristics

figure 7. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

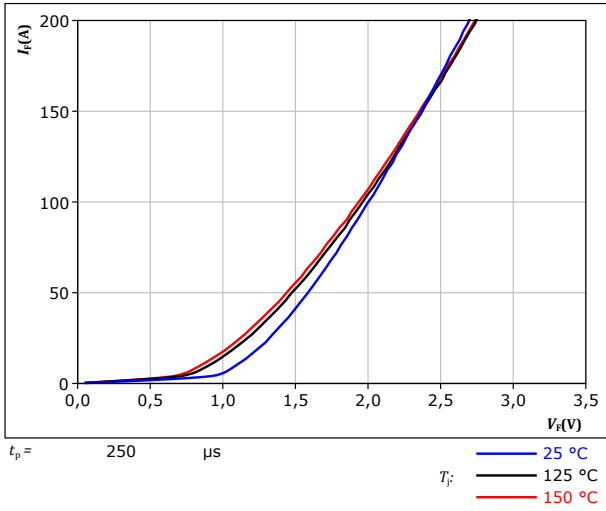
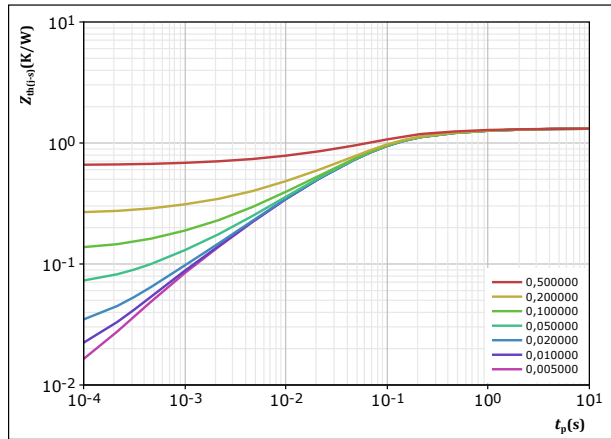


figure 8. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$$D = \frac{t_p}{T} = 1,313 \quad \text{K/W}$$

FWD thermal model values

R (K/W)	τ (s)
8,79E-03	2,76E+01
8,03E-02	1,44E+00
2,22E-01	2,69E-01
6,72E-01	6,22E-02
2,00E-01	1,32E-02
9,38E-02	3,50E-03
4,03E-02	5,88E-04

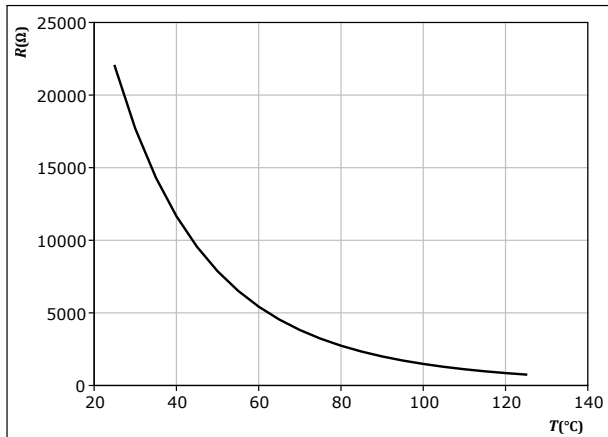


Thermistor Characteristics

figure 9. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

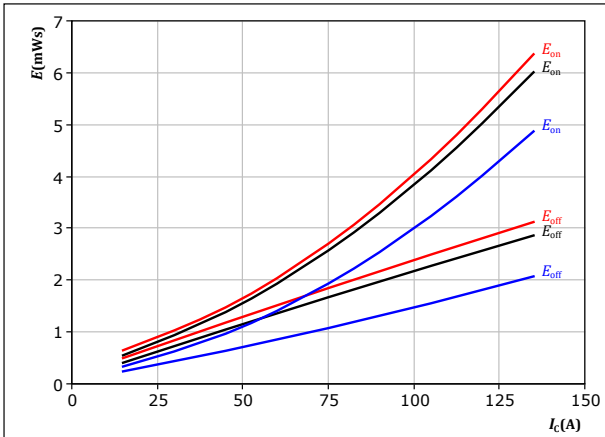




Inverter Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_c)$

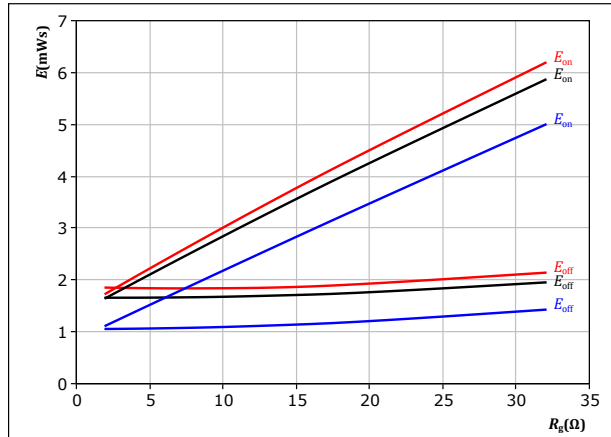


With an inductive load at
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$

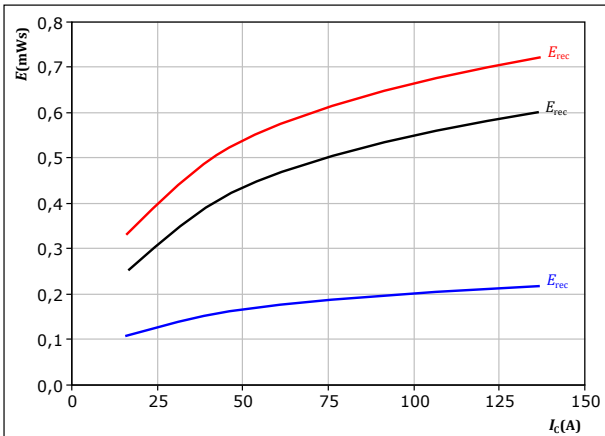


With an inductive load at
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 75$ A

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$

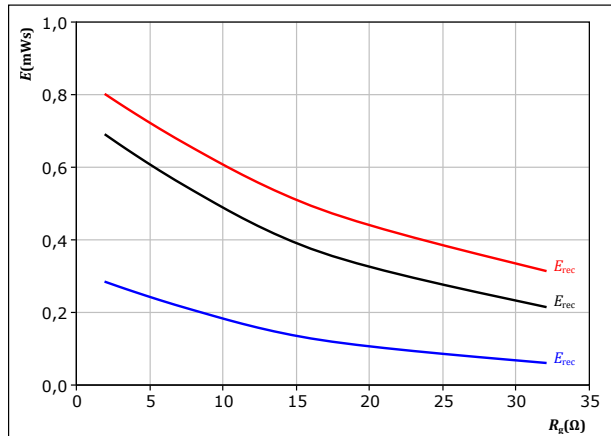


With an inductive load at
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 75$ A

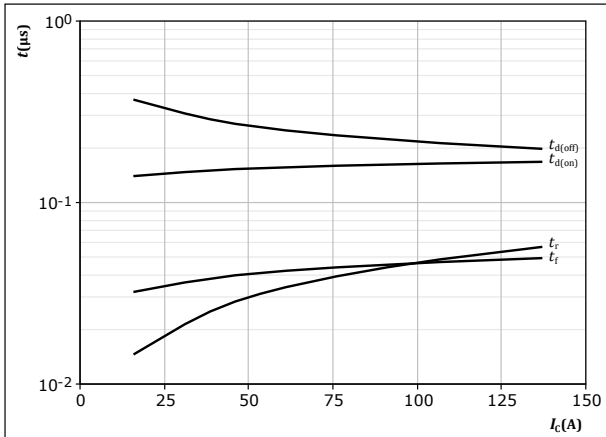
T_j : — 25 °C
 — 125 °C
 — 150 °C



Inverter Switching Characteristics

figure 14. IGBT

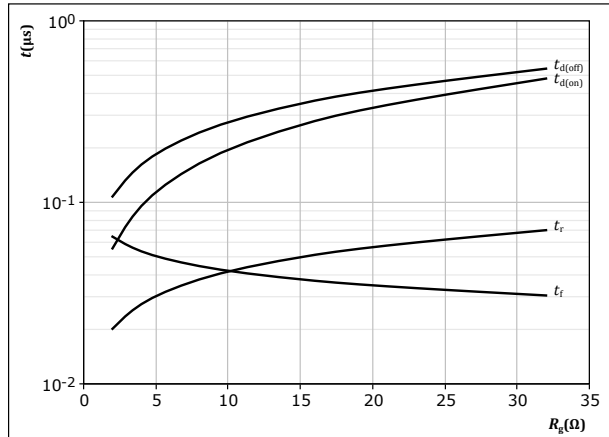
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

figure 15. IGBT

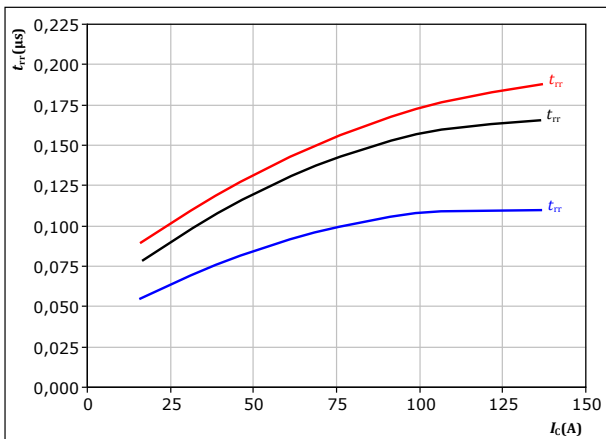
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 75 \text{ A}$

figure 16. FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$

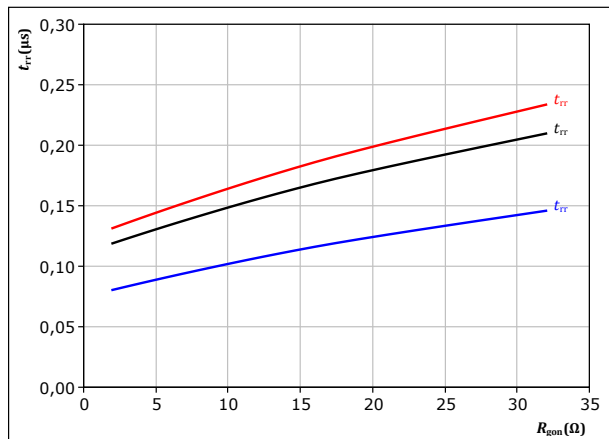


With an inductive load at
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 17. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 75 \text{ A}$

T_j :
— 25 °C
— 125 °C
— 150 °C

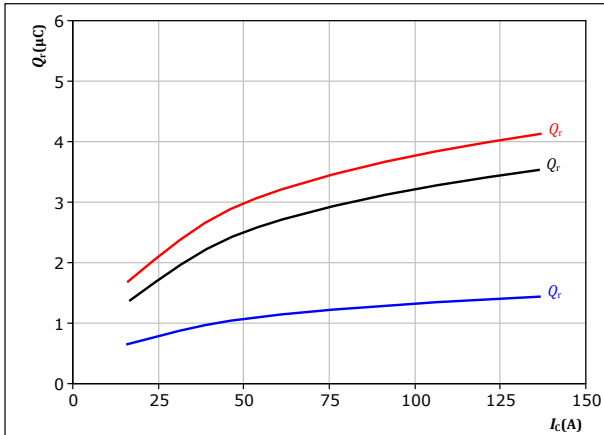


Inverter Switching Characteristics

figure 18. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

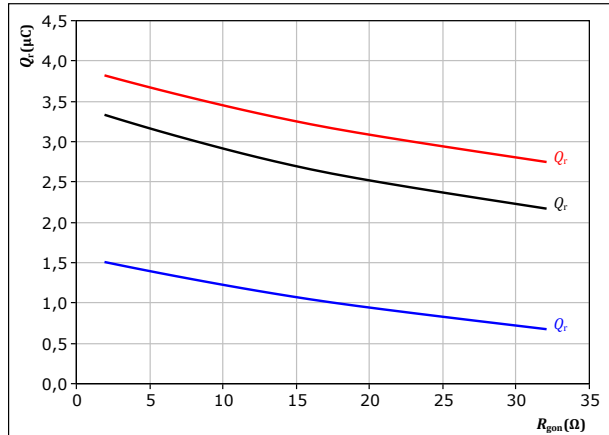
$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 19. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

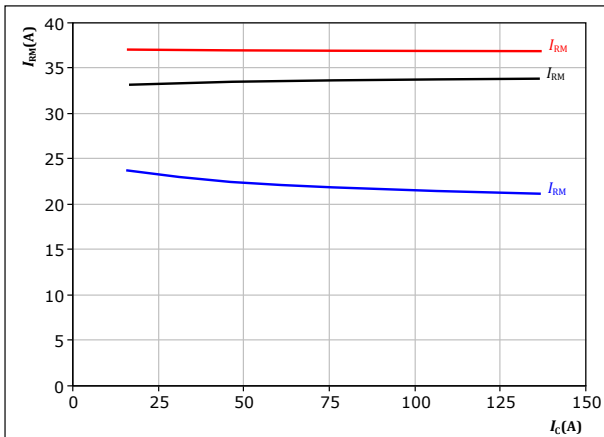
$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 75 \text{ A}$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 20. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

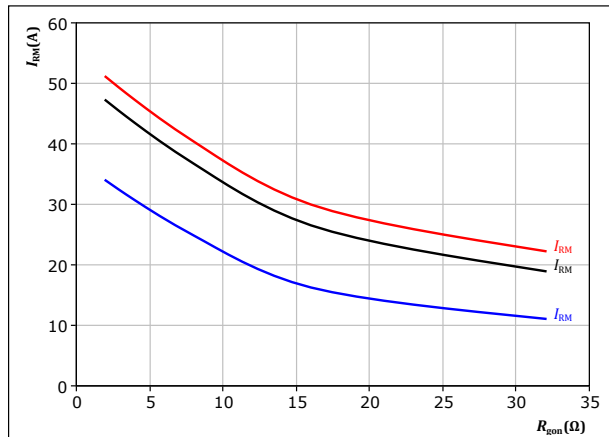
$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 21. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 75 \text{ A}$

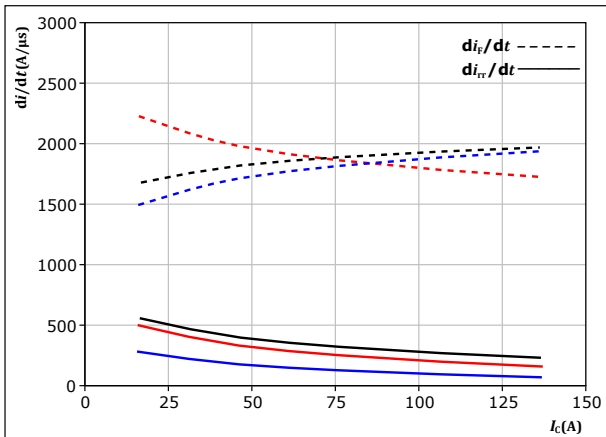
T_j : — 25 °C
— 125 °C
— 150 °C



Inverter Switching Characteristics

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_C)$

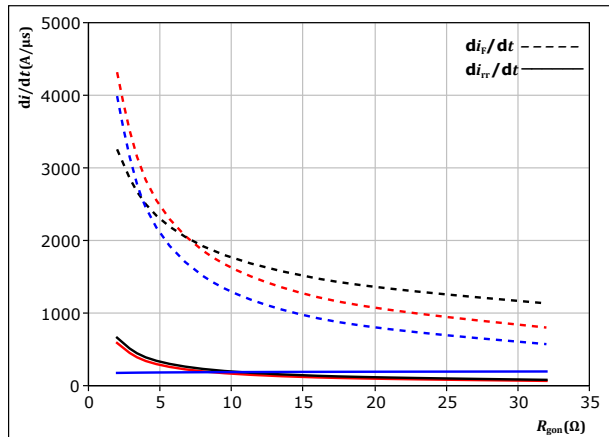


With an inductive load at

$V_{CE} = 350 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}$
$V_{GE} = \pm 15 \text{ V}$	$T_j = 125 \text{ }^\circ\text{C}$
$R_{gon} = 8 \text{ } \Omega$	$T_j = 150 \text{ }^\circ\text{C}$

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{gon})$

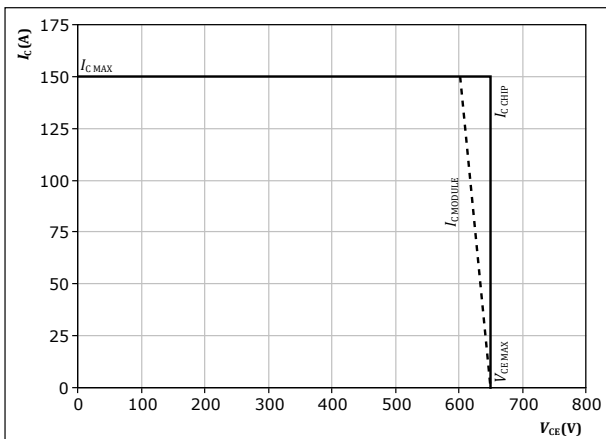


With an inductive load at

$V_{CE} = 350 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}$
$V_{GE} = \pm 15 \text{ V}$	$T_j = 125 \text{ }^\circ\text{C}$
$I_C = 75 \text{ A}$	$T_j = 150 \text{ }^\circ\text{C}$

figure 24. IGBT

Reverse bias safe operating area
 $I_C = f(V_{CE})$



At $T_j = 150 \text{ }^\circ\text{C}$
 $R_{gon} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$



Inverter Switching Definitions

figure 25. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

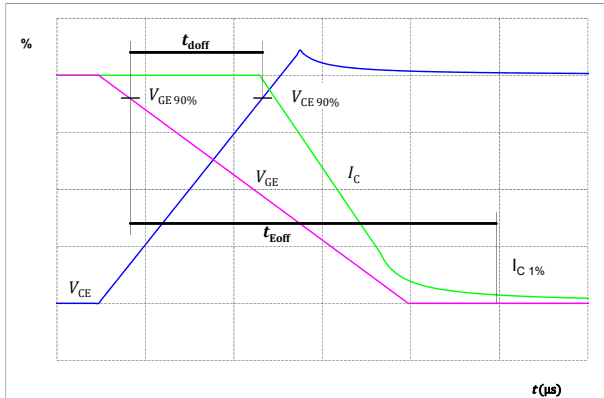


figure 26. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

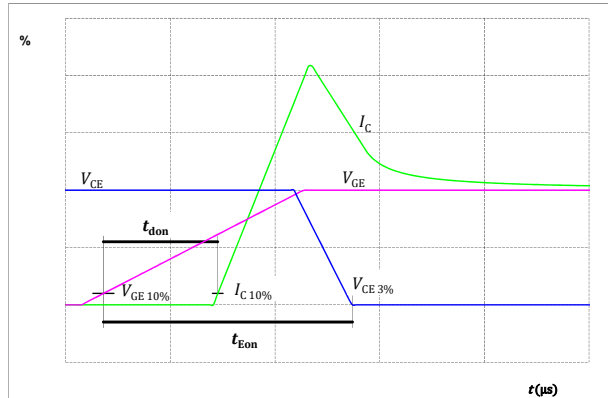


figure 27. IGBT

Turn-off Switching Waveforms & definition of t_f

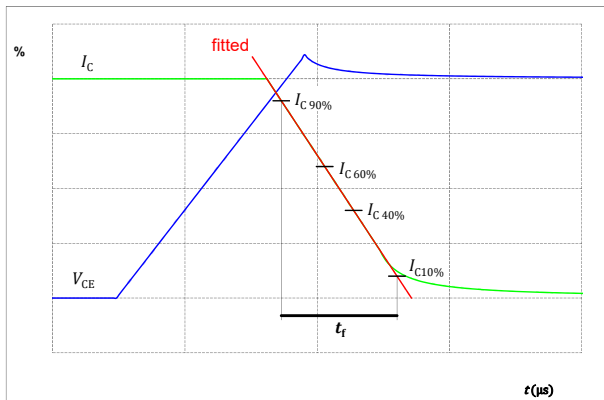
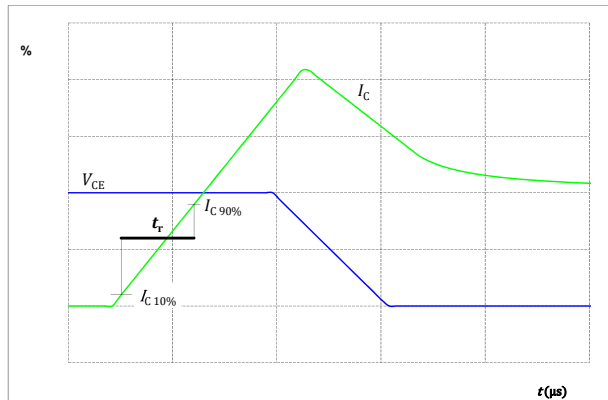


figure 28. IGBT

Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

figure 29. FWD

Turn-off Switching Waveforms & definition of t_{rr}

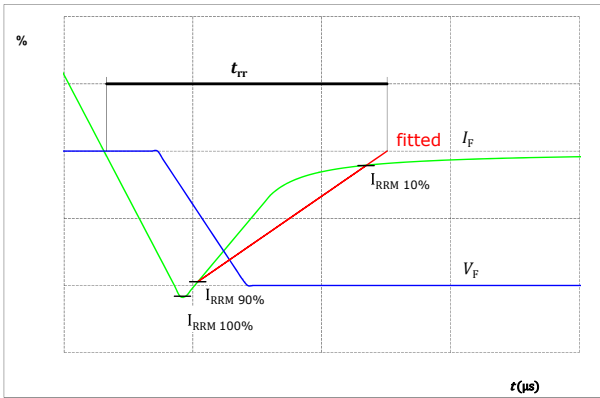
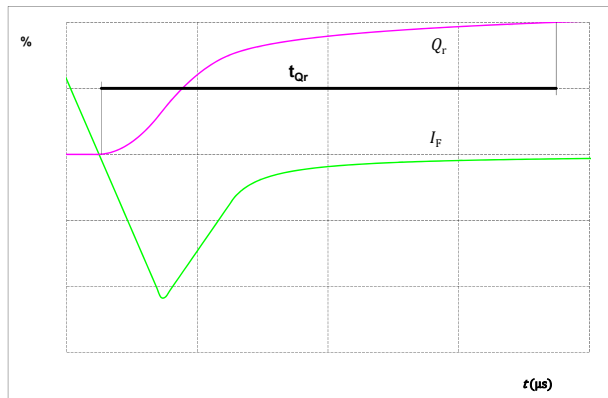


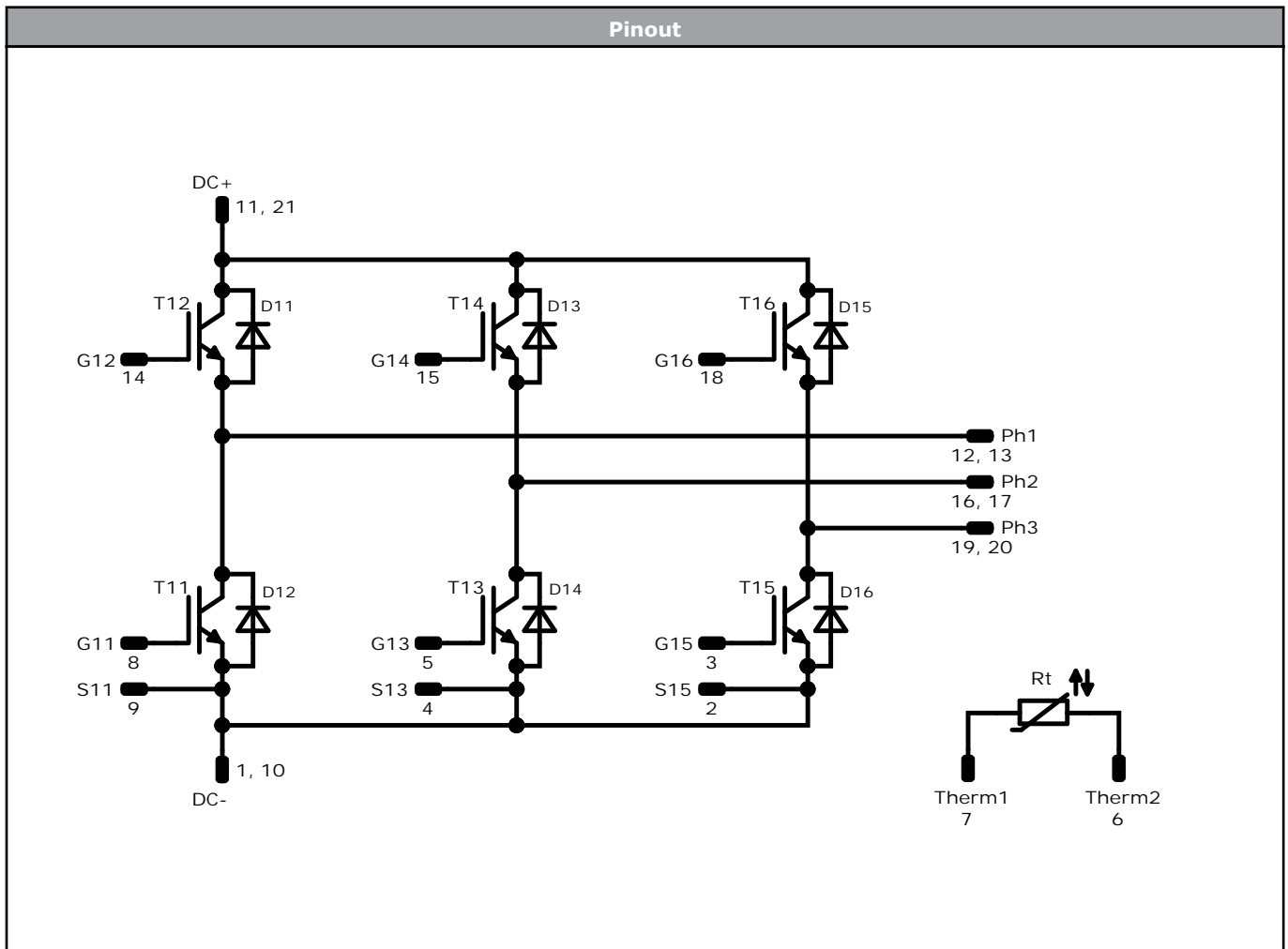
figure 30. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





Vincotech



Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	650 V	75 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	650 V	75 A	Inverter Diode	
Rt	Thermistor			Thermistor	



Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow 0</i> packages see vincotech.com website.

Package data
Package data for <i>flow 0</i> packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}C$ and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.



Document No.:	Date:	Modification:	Pages
10-FZ076PA075I7-P866F08-D1-14	18 Dec. 2024	Initial Release	

DISCLAIMER

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.